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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Yoshimi Takahashi

Docket Number: TI-37029

Serial No.: 10/791,037

Art Unit: 2822

Filed: 03/02/2004

Examiner: K. Duong

For: SYSTEM AND METHOD FOR FORMING MOLD CAPS OVER...

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Jackie McBride

FACSIMILE COVER SHEET

X FACSIMILE COVER SHEET NEW APPLICATION DECLARATION (# Pages) ASSIGNMENT (# Pages) FORMAL DRAWINGS INFORMAL DRAWINGS CONTINUATION APP'N (# Pages)		X RESPONSE TO NON COMPLIANT AMDT. (8 PGS.) X COVER LETTER (1 PG.)
NAME OF INVENTOR(S):		RECEIPT DATE & SERIAL NO.:
TAKAHASHI		Serial No.: 10/791,037 Conf. No: 1260
TITLE OF INVENTION: SYSTEM AND METHOD FOR FORMING		
TI FILE NO.:	DEPOSIT ACCT. NO.:	
TI-37029	20-0668	·
FAXED: 02/03/2006		
DUE: 02/28/2006		
ATTY/SECY: YT/jsm		

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> Texas Instruments Incorporated PO Box 655474, M/S 3999

FEB 0 3 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE PATENT APPLICATION

Application No.

10/791,037

Confirmation No.: 1260

Applicants

Yoshimi Takahashi March 2, 2004

Filed

2822

TC/A.U. Examiner

Duong, Khanh B

Docket No.

TI-37029

Customer No.

23494

RESPONSE TO NON-COMPLIANT AMENDMENT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37
CFR 1.8

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Jackie McBride

Dear Sir;

In response to the Notice of Non-Compliant Amendment mailed Jan. 30, 2006, applicant submits a 2nd Election with Preliminary Amendment which includes original claim 20 that was inadvertently left out of the initial response mailed on Jan. 23, 2006.

Texas Instruments Incorporated P. O. Box 655474 MS 3999 Dallas, TX 75264 (972) 917-5355

Respectfully submitted,

Reg. No. 52,805 Attorney for Applicant

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE PATENT APPLICATION

Application No.

10/791,037

Confirmation No.: 1260

Applicants

Yoshimi Takahashi

Filed

March 2, 2004

TC/A.U.

2822

Examiner

Duong, Khanh B

Docket No.

TI-37029

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23494

RESPONSE TO NON-COMPLIANT AMENDMENT ELECTION WITH PRELIMINARY AMENDMENT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

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India McPrido

Dear Sir:

Responsive to the first Office action of December 29, 2005, and the subsequent Notice of Non-compliance mailed Jan. 30, 2006, applicant amends the above identified application as follows:

Amendments to the Specification begins on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims, which begins on page 3 of this paper.

Remarks begin on page 8 of this paper.